

# **Glass Passivated Single-Phase Bridge Rectifiers**

## FEATURES

- Thin Single in-line low profile package ideal for compact required circuit
- Glass passivated junction
- High surge current capability
- UL Recognized File # E-326243
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC

## MECHANICAL DATA

#### Case: KBJL

Molding compound, UL flammability classification rating 94V-0

Base P/N with suffix "G" on packing code - halogen-free

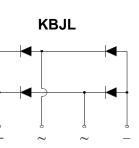
**Terminal:** Matte tin plated leads, solderable per JESD22-B102 Meet JESD 201 class 1A whisker test

Polarity: As marked

**Mounting torque:** 0.56 Nm max. (5 in-lbs. max.) **Weight:** 2.5g (approximately)









PARAMETER	SYMBOL	TS10KL60	TS10KL80	TS10KL100	UNIT
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	420	560	700	V
Maximum DC blocking voltage	V <sub>DC</sub>	600	800	1000	V
Maximum average forward rectified current	I <sub>F(AV)</sub>		10	-	А
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	180		А	
Rating of fusing ( t<8.3ms)	l <sup>2</sup> t	134		A <sup>2</sup> s	
Maximum instantaneous forward voltage (Note 1) $I_F$ = 5 A	V <sub>F</sub>	1.0		V	
Maximum reverse current @ rated VR T <sub>J</sub> =25 $^{\circ}$ C T <sub>J</sub> =100 $^{\circ}$ C	I <sub>R</sub>	5 150		μΑ	
Typical thermal resistance (Note 2)	R <sub>θJC</sub>	1.5		<sup>o</sup> C/W	
Operating junction temperature range	TJ	- 55 to +150		OO	
Storage temperature range	T <sub>STG</sub>	- 55 to +150 °c		°C	

Note 2: Mount on Heatsink size of 4" x 6" x 0.25" Al-Plate



Taiwan Semiconductor

ORDERING INFORMATION				
PART NO. PACKING CODE		GREEN COMPOUND	PACKAGE	PACKING
FARTINO. TAG		CODE		
TS10KLXX (Note 1)	D3	Suffix "G"	KBJL	20 / TUBE

Note 1: "xx" defines voltage from 600V (TS10KL60) to 1000V (TS10KL100)

EXAMPLE					
PREFERRED P/N PART NO. PACKING C		PACKING CODE	GREEN COMPOUND CODE	DESCRIPTION	
TS10KL80 D3	TS10KL80	D3			
TS10KL80 D3G	TS10KL80	D3	G	Green compound	

## RATINGS AND CHARACTERISTICS CURVES

(TA=25 $^\circ\!\!\mathbb{C}$  unless otherwise noted)

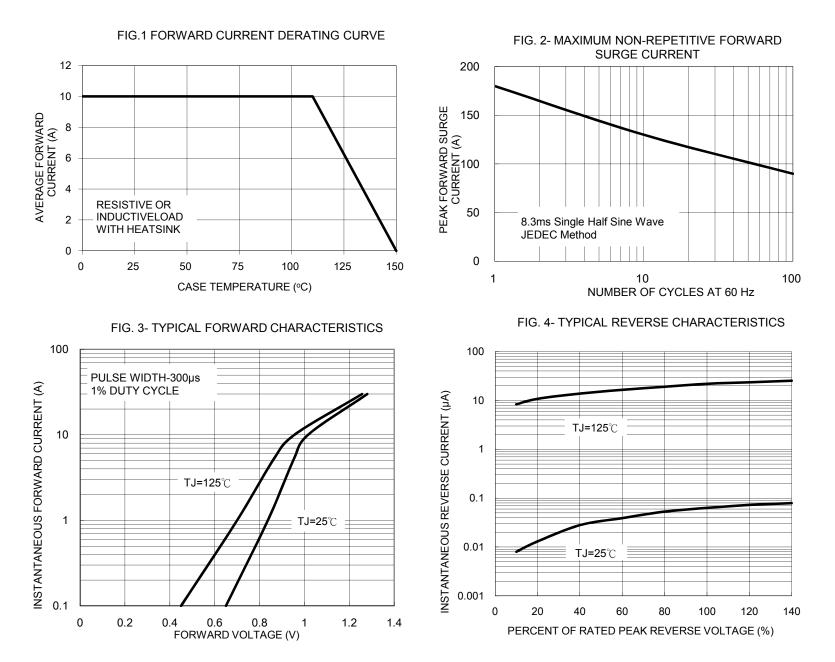
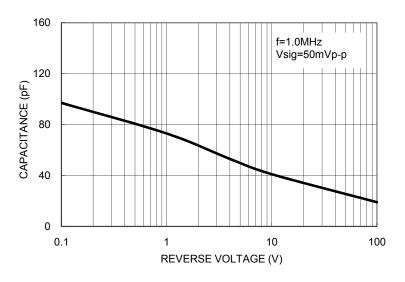
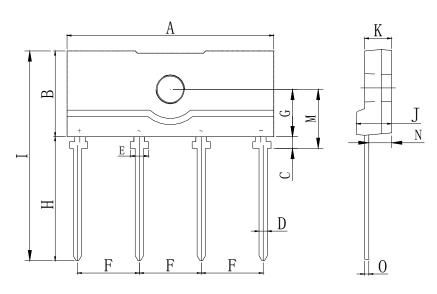




FIG. 5- TYPICAL JUNCTION CAPACITANCE



### PACKAGE OUTLINE DIMENSIONS



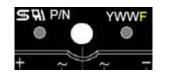
P/N

F

YWW

DIM.	Unit	(mm)	Unit (inch)		
	Min	Мах	Min	Max	
А	24.70	25.30	0.972	0.996	
В	10.00	10.60	0.394	0.417	
С	1.20	1.60	0.047	0.063	
D	0.90	1.10	0.035	0.043	
E	2.10	2.30	0.083	0.091	
F	7.30	7.70	0.287	0.303	
G	5.50	5.90	0.217	0.232	
Н	14.40	15.40	0.567	0.606	
I	24.90	25.50	0.980	1.004	
J	4.00	4.40	0.157	0.173	
K	3.00	3.40	0.118	0.134	
М	6.90	7.30	0.272	0.287	
Ν	2.50	2.90	0.098	0.114	
0	0.30	0.70	0.012	0.028	

#### MARKING DIAGRAM



= Specific Device Code

= Date Code

= Factory Code

Document Number: DS\_D1402001



Taiwan Semiconductor

## Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors inaccuracies.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or seling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.

Document Number: DS\_D1402001